CLAIM AMENDMENTS

1. (Previously cancelled)
2. (Cancelled herein)
3. (Cancelled herein)
4. (Cancelled herein)
5. (Cancelled herein)
6. (Cancelled herein)
7. (Cancelled herein)
8. (Cancelled herein)
9. (Cancelled herein)
10. (Cancelled herein)
11. (Cancelled herein)
12. (Cancelled herein)
13. (Cancelled herein)
14. (Cancelled herein)
15. (Cancelled herein)
16. (Cancelled herein)
17. (Cancelled herein)
18. (Cancelled herein)

19. (New) In combination, an electrically conductive or semi-conductive surface and a current collector structure for collecting current from said electrically conductive or semi-conductive surface, said current collector structure comprising,

- a sheetlike substrate having a first substrate surface,
- a first material overlaying a portion of said first substrate surface, said first material comprising a polymer, and characterized as having a first pattern,
- a second pattern comprising an electrodeposited metal, said second pattern being at least partially defined by said first pattern,

said combination characterized by having said electrodeposited metal in electrical communication with said conductive or semi-conductive surface.

20. (New) The combination of claim 19 wherein said conductive or semi-conductive surface is a light incident surface of a photovoltaic cell.

21. (New) The combination of claim 20 wherein said photovoltaic cell comprises a thin film semiconductor structure.

22. (New) The combination of claim 21 wherein said thin film semiconductor structure is supported on a metal based foil.

23. (New) The combination of claim 19 wherein said conductive or semi-conductive surface comprises a transparent conductive oxide.

24. (New) The combination of claim 19 wherein said current comprises a photogenerated current.

25. (New) The combination of claim 19 wherein at least a portion of said first substrate surface is laminated to said conductive or semi-conductive surface.

26. (New) The combination of claim 19 wherein said first substrate surface comprises a polymeric adhesive.

27. (New) The combination of claim 26 wherein said first substrate surface is adhesively bonded to said conductive or semi-conductive surface.

28. (New) The combination of claim 19 wherein said sheetlike substrate comprises multiple material layers.

29. (New) The combination of claim 19 wherein said sheetlike substrate comprises silicon.

30. (New) The combination of claim 19 wherein said sheetlike substrate comprises glass.

31. (New) The combination of claim 19 wherein said electrodeposited metal comprises multiple fingers, said multiple fingers joined by a buss, and wherein said multiple fingers and said buss are formed at least in part by a continuous electrodeposited metal forming portions of both said multiple fingers and said buss.

32. (New) The combination of claim 19 wherein said first material comprises printed material.

33. (New) The combination of claim 19 wherein said first material comprises a material component characterized as having the ability to assist deposition of metal.

34. (New) The combination of claim 33 wherein said material component is an electrically conductive polymer.

35. (New) The combination of claim 33 wherein said material component is a directly electroplateable resin (DER).

36. (New) The combination of claim 33 wherein said material component comprises a seed catalyst suitable for initiating chemical metal deposition.

37. (New) The combination of claim 19 wherein said electrodeposited metal comprises a Group VIII metal.

38. (New) The combination of claim 19 wherein said electrodeposited metal comprises a metal chosen from the group nickel, copper or silver.

39. (New) The combination of claim 19 wherein said second pattern comprises a low melting point metal based material.

40. (New) The combination of claim 39 wherein said second pattern comprises indium.

41. (New) In combination, a light incident surface of a photovoltaic cell and an electrical interconnect structure, said interconnect structure overlaying and in electrical communication with at least a portion of said surface, said interconnect structure comprising,

- a base substrate,
- a material characterized as having the ability to assist in deposition of metal, said material comprising a polymer,
- a metal overlaying at least a portion of said material.

42. (New) The combination of claim 41 wherein said interconnect structure is in electrical communication with a second distinct conductive surface.

43. (New) The combination of claim 41 wherein said interconnect structure extends to a region outside a peripheral boundary of said light incident surface.

44. (New) In combination, an electrically conductive or semi-conductive surface and a current collector structure, said current collector structure comprising one or more

electrical traces overlaying a sheetlike substrate, said traces comprising a material having the ability to assist metal deposition, said material having a first surface and an oppositely facing second surface, said first surface facing said substrate and being devoid of metal coating and said second surface being coated with metal, said metal in electrical communication with said conductive or semi-conductive surface.